

## 产 品 规 格 书

### SPECIFICATIONS FOR PRODUCT

产品类型 TYPE : SMD3225

产品规格 SPEC : 25MHz/3225/18PF/10PPM

产品型号 P/N : CJ13-250001810A10

日期 DATE : 2018/12/05

核准及签名			部门
R&D APPR. SIGNATURED			DEPT.
拟制	审核	批准	频率器件事业部
ISSUE	CHECK	APPROVAL	
王嘉诚 2018/12/05	许秋菊 2018/12/05	杨立新 2018/12/05	

江 苏 长 晶 科 技 有 限 公 司

JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

地址：中国江苏省南京江北新区产业技术研创园江淼路88号腾飞大厦C座13楼

Add: 13Th Floor, C Block, Tengfei Building, No. 88 Jiangmiao Rd. Pukou

District, Nanjing City, Jiangsu Province, China



**SMCE3225 4 pads Crystal Resonator**

**CJ13-250001810A10**

1. Scope:

- 1.1 This specification applies to the RoHS/SONY compliance quartz crystal unit with a frequency of 25MHz which will be used in crystal oscillator applications.

2. Construction:

- 2.1 Type of Quartz Resonator: SMCE3225 4pads

3. Electrical Characteristics

- |  |                            |
|--|----------------------------|
| 3.1 Nominal Frequency(f):                            | 25MHz                      |
| 3.2 Load Capacitance( $C_L$ ):                       | 18pF                       |
| 3.3 Frequency Tolerance( $\Delta f/f$ ):             | $\pm 10\text{ppm}$         |
| 3.4 Frequency Temperature Stability:                 | $\pm 10\text{ppm}$         |
| 3.5 Resonance Resistance(ohm):                       | 60ohms Max                 |
| 3.6 Osc mode:  | Fundamental mode           |
| 3.7 Shunt Capacitance( $C_0$ ):                      | $< 2\text{pF}$             |
| 3.8 Drive Level( $D_L$ ):                            | $< 100\mu\text{W}$         |
| 3.9 Operating Temperature Range( $T_{\text{OPR}}$ ): | -20 to + 70                |
| 3.10 Storage Temperature Range( $T_{\text{STG}}$ ):  | -55 to + 125°C             |
| 3.11 Insulation Resistance(IR):                      | $> 500\text{ M ohms}$      |
| 3.12 Aging( $\Delta f_A$ ):                          | $\pm 3\text{ppm per Year}$ |

## 4. Reliability Specifications

This is the quality control and quality assurance and reliability tests performance data for the RoHS/

SONY compliance 25MHz SMCE3225 4pads crystal resonators

related to the specification and approval sheet provided by JSCJ .

Standard test condition (TEMP.: 20±5°C. Relative humidity: 65±20%)

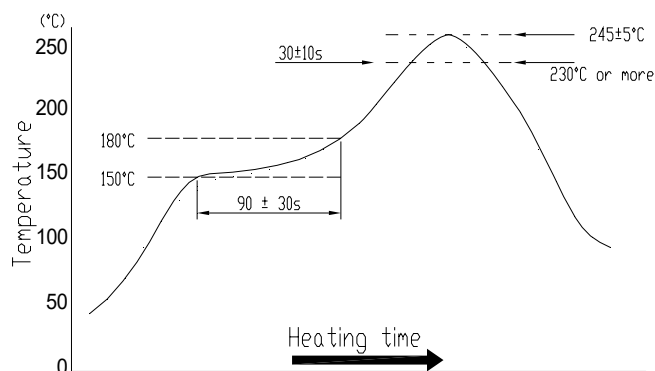
For any discrepancy in GO/NG, test will be done at TEMP.25±2°C, R.H. 65±5%.

NO.	PROCESS	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3-2006, Method Cab)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 96 hrs at 40 °C ± 3 °C, with 93 %R.H. Then keep the DUT in dry oven at 40 ± 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours.
4.5	Vibration (GB/T 2423.10-1995, Method Fc)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Apply 0.75mm vibration at sweep frequency 10~500 Hz, 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms. and exhibit no visible damage.	Peak 1000m/s <sup>2</sup> , normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms. and exhibit no visible damage.	Free drop to the steel plate with thickness of 3 mm from 1.00 m heights for 3 times.
4.8	Solderability ( IEC60068-2-58, Test Td: )	Terminals shall be covered more then 95% with solder.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 20s ± 5s at 235°C, peak soldering time for 10s ± 1s between 240 and 250°C. There is no need to do functional test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C-6429 Method 1 & 2 )	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 1.8kg for at least 60 seconds.
4.10	Resistance to Soldering Heat (IEC60068-2-58, Test Td: Table 4)	Frequency change after test $\leq \pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 60s max at 235°C, peak soldering time for 20s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours.
4.11	OTHERS		

## 5. Recommended Reflow soldering condition (SMD)

Solder profile

Peak:  $245 \pm 5^{\circ}\text{C}$  Soldering zone:  $230^{\circ}\text{C}$  or more,  $30 \pm 10\text{s}$ . Pre-heating zone 1:  $150 \sim 180^{\circ}\text{C}$ ,  $90 \pm 30\text{s}$



Temperature profile for reflow soldering

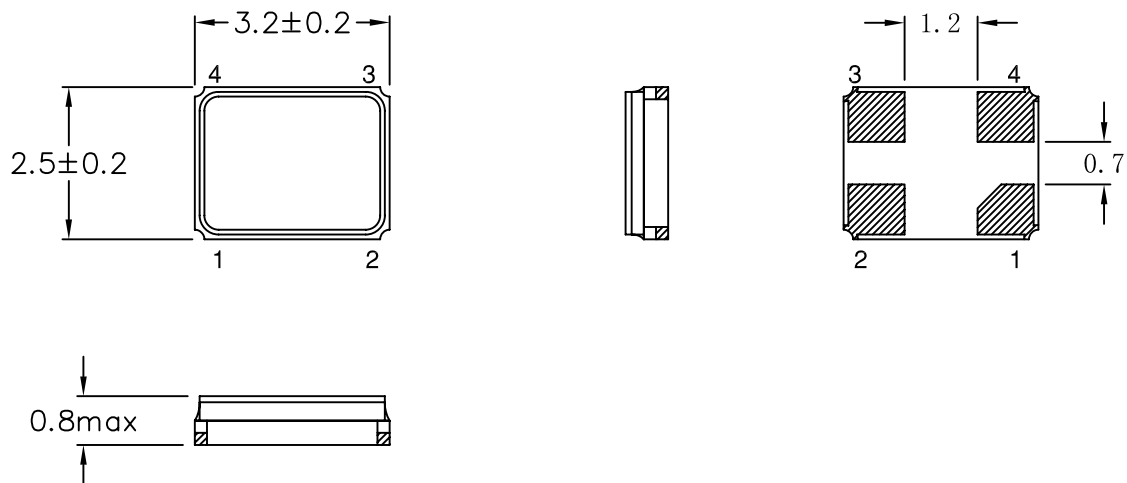
## 6. Soldering iron method

Bit temperature:  $350 \pm 10^{\circ}\text{C}$  Application time of soldering iron:  $3 \pm 1\text{ s}$ . For other procedures, refer to IEC 60068-2-20.

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## Package Outline Dimensions

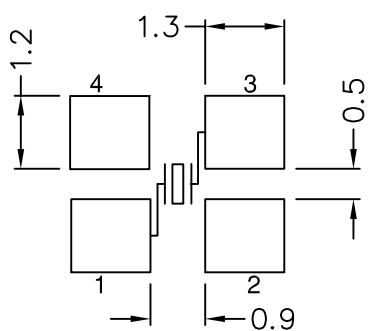
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## Suggested Pad Layout

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